

CMOS 8-BIT SINGLE-CHIP MICROCOMPUTER (TLCS-48C)

TMP80C50AP/TMP80C50AP-6
TMP80C40AP/TMP80C40AP-6
TMP80C50AU/TMP80C50AU-6

1. GENERAL DESCRIPTION AND FEATURES

The TMP80C50A is a single chip microcomputer fabricated in Silicon Gate CMOS technology which provides internal 8-bit parallel architecture.

The following basic architectural functions of a computer have been included in a single chip; an 8-bit CPU, 256×8 RAM data memory, $4K \times 8$ ROM program memory, 27 I/O lines and an 8-bit timer/event counter.

The TMP80C50A is particularly efficient as a controller. It has extensive bit handling capability as well as facilities for both binary and BCD arithmetic.

The TMP80C40A/-6 is the equivalent of a TMP80C50A/-6 without ROM program memory on chip. By using this device with external EPROM or RAM, software debugging becomes easy.

The TMP80C50AP/-6 and TMP80C40AP/-6 are in a standard Dual Inline Package.

The TMP80C50AU/-6 is in a 44-pin Micro Flat Package.

FEATURES

- TMP80C50AP/TMP80C40AP/TMP80C50AU
1.36 μ s Instruction Cycle Time – 40°C to 85°C, 5V $\pm$ 10%
- TMP80C50AP-6/TMP80C40AP-6/TMP80C50AU-6
2.5 μ s Instruction Cycle Time – 40°C to 85°C, 5V $\pm$ 20%
- Software Upward Compatible with TMP8049AP/INTEL's 8049.
- $4K \times 8$ masked ROM / 256×8 RAM
- Low Power
10mA MAX. in Normal Operation ($V_{CC} = 5V$, $f_{XTAL} = 6MHz$)
10 μ A MAX. in Power Down Mode ($V_{CC} = 5V$, $f_{XTAL} : DC$)
- Power Down Mode (Stand-by Mode)
- Halt Mode (Idle Mode)

2. PIN CONNECTIONS AND PIN FUNCTIONS

2.1 Pin Connections (Top View)

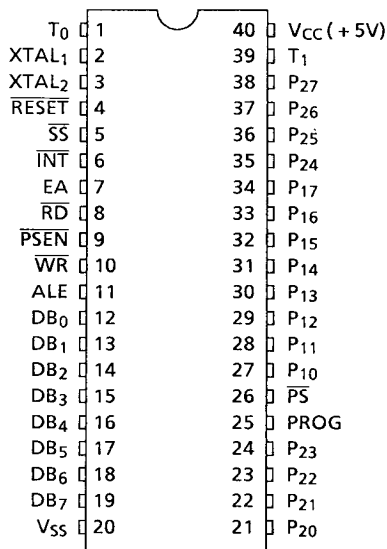


Figure 2.1 (1) DIP Pin Connections

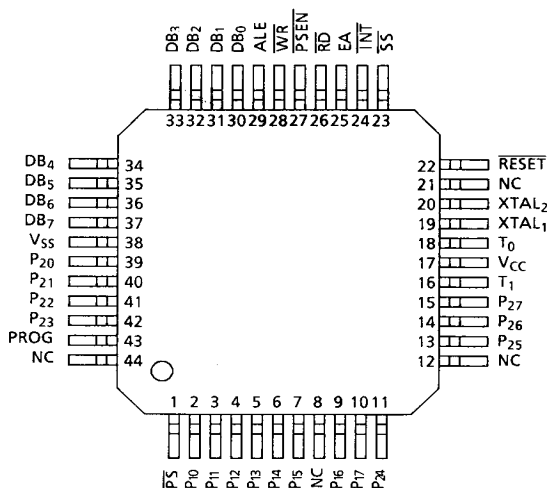


Figure 2.1 (2) Micro Flat Package Pin Connections

2.2 Pin Names And Pin Description

- V_{SS} (Power Supply)
Circuit GND potential
- V_{CC} (Power Supply)
+5V during operation
- $\overline{PS}$ (Input)
The control signal for the power saving at the power down mode (Active Low)
- PROG (Output)
Output strobe for the TMP82C43P I/O expander.
- P_{10} - P_{17} (Input/Output) Port1
8-bit quasi-bidirectional port (Internal Pullup=50K Ω).
- P_{20} - P_{27} (Input/Output) Port2
8-bit quasi-bidirectional port (Internal Pullup=50K Ω).
 P_{20} - P_{23} contain the four high order program counter bits during an external program memory fetch and serve as a 4-bit I/O expander bus for the TMP82C43P.
- DB_0 - DB_7 (Input/Output, Tri-State)
True bidirectional port which can be written or read synchronously using the $\overline{RD}$, $\overline{WR}$ strobes. The port can also be statically latched. Contains the 8 low order program counter bits during an external program memory fetch, and receives the addressed instruction under the control of $\overline{PSEN}$.
Also contains the address and data during an external RAM data store instruction, under control of ALE, $\overline{RD}$, and $\overline{WR}$.
- T_0 (Input/Output)
Input pin testable using the conditional transfer instructions JT0 and JNT0. T_0 can be designated as a clock output using ENT0 CLK instruction.
- T_1 (Input)
Input pin testable using the JT1 and JNT1 instruction. Can be designated the event counter input using the timer/STRT CNT instruction.
- $\overline{INT}$ (Input)
External interrupt input. Initiates an interrupt if interrupt is enabled. Interrupt is disabled after a reset. Also testable with conditional jump instruction. (Active low)

- $\overline{RD}$ (Output)

Output strobe activated during a Bus read. Can be used to enable data onto the Bus from an external device. Used as a Read Strobe to External Data Memory (Active Low).
- $\overline{WR}$ (Output)

Output strobe during a Bus write (Active Low). Used as a Write Strobe to External Data Memory.
- $\overline{RESET}$ (Input)

Active Low signal which is used to initialize the Processor. Also used during the power down mode.
- ALE (Output)

Address Latch Enable. This signal occurs once during each cycle and is useful as a clock output. The negative edge of ALE strobes address into external data and program memory.
- $\overline{PSEN}$ (Output)

Program Store Enable. This output occurs only during a fetch to external program memory (Active Low).
- $\overline{SS}$ (Input)

Single step input can be used in conjunction with ALE to "single step" processor through each instruction when $\overline{SS}$ is low the CPU is placed into a wait state after it has completed the instruction being executed. Also used during the power down mode.
- EA (Input)

External Access input which forces all program memory fetches to reference external memory. Useful for emulation and debug and essential for testing and program verification. (Active High)
- XTAL₁ (Input)

One side of crystal input for internal oscillator. Also input for external source.
- XTAL₂ (Input)

Other side of crystal input.

3. MACHINE INSTRUCTION

The following symbols and codes are used in the list of machine instruction.

Symbol	Meaning
Rr	Working register ($0 < r < 7$)
Pp	I/O port address P; ($0 < p < 7$)
JBb	Branch instruction in accordance with bit content (b) of operand
aH	Higher order 3 bits of a
aM	Medium order 4 bits of a
aL	Lower order 4 bits of a
aML	Medium order or lower order 8 bits of a
(a)	Content of a
[(a)]	Content of RAM addressed by a
EXT[(a)]	Content of external RAM addressed by a
PRO[(a)]	Content of ROM addressed by a
a<m>	Value at bit position m of a
a<m:n>	Value at bit position m to n of a
a←b	Store a into b
a↔b	Exchange a for b
.	Connection
$\bar{a}$	1 complement of a
a+b	a plus b (Addition)
a-b	a minus b (Subtraction)
a^b	Logical AND for a and b
a∨b	Logical OR for a and b
a⊕b	Exclusive OR for a and b
a=b	a is equal to b
a<>b	a is not equal to b
(a) BCD	Converted value of accumulator

List of TLCS-48 Machine Instruction (1/4)

ITEM	Assembler Mnemonic	Object Code (1st) (2nd)		Function	Flag C, AC	Cycle
		Bin	Hex			
Accumulator Instruction	ADD A, Rr	01101rrr	68+r	(A)←(A)+(Rr) r=0~7	↑↑	1
	ADD A, @Rr	0110000r	60+r	(A)←(A)+[(Rr)] r=0,1	↑↑	1
	ADD A, #i	00000011	03	(A)←(A)+i	↑↓	2
		iiiiiii	ii			
	ADDC A, Rr	01111rrr	78+r	(A)←(A)+(Rr)+(c) r=0~7	↑↑	1
	ADDC A, @Rr	0111000r	70+r	(A)←(A)+[(Rr)]+(c) r=0,1	↑↑	1
	ADDC A, #i	00010011	13	(A)←(A)+i+(c)	↑↓	2
		iiiiiii	ii			
	ANL A, Rr	01011rrr	58+r	(A)←(A) ∧ (Rr) r=0~7		1
	ANL A, @Rr	0101000r	50+r	(A)←(A) ∧ [(Rr)] r=0,1		1
	ANL A, #i	01010011	53	(A)←(A) ∧ i		2
		iiiiiii	ii			
	ORL A, Rr	01001rrr	48+r	(A)←(A) ∨ (Rr) r=0~7		1
	ORL A, @Rr	0100000r	40+r	(A)←(A) ∨ [(Rr)] r=0,1		1
	ORL A, #i	01000011	43	(A)←(A) ∨ i		2
		iiiiiii	ii			
	XRL A, Rr	11011rrr	D8+r	(A)←(A) ⊕ (Rr) r=0~7		1
	XRL A, @Rr	1101000r	D0+r	(A)←(A) ⊕ [(Rr)] r=0,1		1
	XRL A, #i	11010011	D3	(A)←(A) ⊕ i		2
		iiiiiii	ii			
	INC A	00010111	17	(A)←(A)+1		1
	DEC A	00000111	07	(A)←(A)-1		1
	CLR A	00100111	27	(A)←0		1
	CPL A	00110111	37	(A)←NOT(A)		1
	DA A	01010111	57	(A)←(A)BCD	↑	1
	SWAP A	01000111	47	(A)<7:4> ↔ (A)<3:0>		1
	RL A	11100111	E7	(A)<n+1> ← (A)<n> (A)<0> ← (A)<7> n=0~6		1
	RLC A	11110111	F7	(A)<n+1> ← (A)<n> (C)←(A)<7> (A)<0> ← (C) n=0~6	↑	1
	RR A	01110111	77	(A)<n> ← (A)<n+1> n=0~6 (A)<7> ← (A)<0>		1
	RRC A	01100111	67	(A)<n> ← (A)<n+1> (C)←(A)<0> (A)<7> ← (C) n=0~6	↑	1
I/O	IN A, Pp	000010pp	08+p	(A)←(Pp) P=1,2		2
	OUTL Pp, A	001110pp	38+p	(Pp) ← (A) P=1,2		2
	ANL Pp, #i	100110pp	98+p	(Pp) ← (Pp) ∧ i P=1,2		2
	ORL Pp, #i	100010pp	88+p	(Pp) ← (Pp) ∨ i P=1,2		2

List of TLCS-48 Machine Instruction (2/4)

ITEM	Assembler Mnemonic	Object Code (1st) (2nd)		Function	Flag C, AC	Cycle
		Bin	Hex			
I/O	INS A, BUS	00001000	08	(A)←(BUS)		2
	OUTL BUS, A	00000010	02	(BUS)←(AC)		2
	ANL BUS, #i	10011000	98	(BUS)←(BUS) ∧ i		2
		iiiiiii	ii			
	ORL BUS, #i	10001000	88	(BUS)←(BUS) ∨ i		2
		iiiiiii	ii			
	MOVD A, Pp	000011pp	0C+p	(A)<3:0> ←(Pp) p=4~7 (A)<7:4> ←0		2
(1)	MOVD Pp, A	001111pp	3C+p	(Pp) ←(A)<3:0> p=4~7		2
	ANLD Pp, A	100111pp	9C+p	(Pp) ←(Pp) ∧ (A)<3:0> p=4~7		2
	ORLD Pp, A	100011pp	8C+p	(Pp) ←(Pp) ∨ (A)<3:0> p=4~7		2
	INC Rr	00011rrr	18+r	(Rr) ←(Rr)+1 r=0~7		1
	INC @Rr	0001000r	10+r	[(Rr)] ←[(Rr)]+1 r=0,1		1
	DEC Rr	11001rrr	C8+r	(Rr) ←(Rr)-1 r=0~7		1
Branch Instruction	JMP a	aH00100	aH+4	(PC)<10:0> ←a (PC)<11> ←(DBF)		2
	JMPP @A	10110011	B3	(PC)<7:0>←PRO[(PC)<11:8>·(A)]		2
	DJNZ Rr, a	11101rrr	E8+r	(Rr) ←(Rr)-1 r=0~7 if(Rr) ≠0 then(PC)<7:0>←aML else no operation		2
		aML				
	JC a	11110110	F6	if(C)=1 then(PC)<7:0>←aML else no operation		2
		aML				
	JNC a	11100110	E6	if(C)=0 then(PC)<7:0>←aML else no operation		2
		aML				
	JZ a	11000110	C6	if(A)=0 then(PC)<7:0>←aML else no operation		2
		aML				
	JNZ a	10010110	96	if(A)≠0 then(PC)<7:0>←aML else no operation		2
		aML				
	JTO a	00110110	36	if T0=1 then(PC)<7:0>←aML else no operation		2
		aML				
	JNTO a	00100110	26	if T0=0 then(PC)<7:0>←aML else no operation		2
		aML				
	JT1 a	01010110	56	if T1=1 then(PC)<7:0>←aML else no operation		2
		aML				
	JNT1 a	01000110	46	if T1=0 then(PC)<7:0>←aML else no operation		2
		aML				
	JF0 a	10110110	B6	if F0=1 then(PC)<7:0>←aML else no operation		2
		aML				
	JF1 a	01110110	76	if F1=1 then(PC)<7:0>←aML else no operation		2
		aML				
	JTF a	00010110	16	if TF=1 then(PC)<7:0>←aML else no operation		2
		aML				

(1) Register Instruction

List of TLCS-48 Machine Instruction (3/4)

ITEM	Assembler Mnemonic	Object Code (1st) (2nd)		Function	Flag C, AC	Cycle
		Bin	Hex			
(2)	JNI a	10000110 aML	86	if INT =0 then(PC)<7:0>←aML else no operation		2
	JBB a	bbb10010 aML	b+12	if (A)=1 then (PC)<7:0>←aML else no operation b=0~7		2
(3)	CALL a	aH10100 aML	aH+14	[(SP)] ←(PSW)<7:4>·(PC) (SP) ←(SP)+1 (PC)<10:0> ←a (PC)<11> ←(DBF)		2
	RET	10000011	83	(SP)←(SP)-1 (PC) ←[(SP)]<11:0>		2
	RETR	10010011	93	(SP)←(SP)-1 (PC) ←[(SP)]<11:0> (PSW)<7:4> ←[(SP)]<15:12>	↑ ↓	2
(4)	CLR C	10010111	97	(C)←0		1
	CPL C	10100111	A7	(C)←NOT(C)		1
	CLR F0	10000101	85	(F0) ←0		1
	CPL F0	10010101	95	(F0) ←NOT(F0)		1
	CLR F1	10100101	A5	(F1) ←0		1
	CPL F1	10110101	B5	(F1) ←NOT(F1)		1
Move Instruction	MOV A, Rr	11111rrr	F8+r	(A)←(Rr) r=0~7		1
	MOV A, @Rr	1111000r	F0+r	(A)←[(Rr)] r=0,1		1
	MOV A, #i	00100011 iiiiiii	23 ii	(A) ←i		2
	MOV Rr, A	10101rrr	A8+r	(Rr)←(A) r=0~7		1
	MOV @Rr, A	1010000r	A0+r	[(Rr)]←(A) r=0,1		1
	MOV Rr, #i	10111rrr iiiiiii	B8+r ii	(Rr)←i r=0~7		2
	MOV @Rr, #i	1011000r iiiiiii	B0+r ii	[(Rr)]←i r=0,1		2
	MOV A, PSW	11000111	C7	(A) ←(PSW)		1
	MOV PSW, A	11010111	D7	(PSW) ←(A)		1
	XCH A, Rr	00101rrr	28+r	(A) ↔(Rr) r=0~7		1
	XCH A, @Rr	0010000r	20+r	(A) ↔[(Rr)] r=0,1		1
	XCHD A, @Rr	0011000r	30+r	(A)<3:0> ↔[(Rr)<3:0>] r=0,1		1
	MOVX @Rr, A	1001000r	90+r	EXT[(Rr)] ←(A) r=0,1		1
	MOVX A, @Rr	1000000r	80+r	(A) ←EXT[(Rr)] r=0,1		1
	MOV P A, @A	10100011	A3	(A) ←PRO[(PC)<11:8>·(A)]		1
	MOV P3 A, @A	11100011	E3	(A) ←PRO[(PC)<11>·011·(A)]		1

(2) Branch Instruction (3) Subroutine Instruction
 (4) Flag Instruction

List of TLCS-48 Machine Instruction (4/4)

ITEM	Assembler Mnemonic	Object Code (1st) (2nd)		Function	Flag C, AC	Cycle
		Bin	Hex			
Timer Counter	MOV A,T	01000010	42	(A) ←(TR)		1
	MOV T,A	01100010	62	(TR)←(A)		1
	STRT T	01010101	55	Start Timer		1
	STRT CNT	01000101	45	Start Counter		1
	STOP TCNT	01100101	65	Stop Timer/Counter		1
	EN TCNTI	00100101	25	Enable Timer/Counter Interrupt		1
	DIS TCNTI	00110101	35	Disable Timer/Counter Interrupt		1
Control	EN I	00000101	05	Enable External Interrupt		1
	DIS I	00010101	15	Disable External Interrupt		1
	SEL RB0	11000101	C5	(BS)← 0		1
	SEL RB1	11010101	D5	(BS)← 1		1
	SEL MB0	11100101	E5	(DBF) ← 0		1
	SEL MB1	11110101	F5	(DBF) ← 1		1
	ENTO CLK	01110101	75	Enable Clock Output on To		1
	HALT	00000001	01	Halt		1
(5)	NOP	00000000	00	no operation		1

(5) Other

4. ELECTRICAL CHARACTERISTICS

4.1 Absolute Maximum ratings

TMP80C50AP/C40AP/C50AU

SYMBOL	ITEM	RATING
V _{CC}	V _{CC} Supply Voltage (with respect to GND (V _{SS}))	- 0.5V to + 7V
V _{INA}	Input Voltage (Except EA)	- 0.5V to V _{CC} + 0.5V
V _{INB}	Input Voltage (Only EA)	- 0.5V to 13V
P _D	Power Dissipation (Ta = 85°C)	250mW
T _{SDR}	Soldering Temperature (Soldering Timer 10 sec)	260°C
T _{STG}	Storage Temperature	- 65°C to 150°C
T _{OPR}	Operating Temperature	- 40°C to 85°C

4.2 DC Characteristics

TMP80C50AP/C40AP/C50AU

T_{OPR} = - 40°C to 85°C, V_{CC} = + 5V ± 10%, V_{SS} = 0V, unless otherwise noted.

SYMBOL	PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{IL}	Input Low Voltage (Except XTAL ₁ , XTAL ₂ , RESET)		- 0.5	—	0.8	V
V _{IL1}	Input Low Voltage (XTAL ₁ , XTAL ₂ , RESET)		- 0.5	—	0.6	V
V _{IH}	Input High Voltage (Except XTAL ₁ , XTAL ₂ , RESET, PS)		2.2	—	V _{CC}	V
V _{IH1}	Input High Voltage (XTAL ₁ , XTAL ₂ , RESET, PS)		0.7 × V _{CC}	—	V _{CC}	V
V _{OL}	Output Low Voltage (Except P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)	I _{OL} = 1.6mA	—	—	0.45	V
V _{OL1}	Output Low Voltage (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)	I _{OL} = 1.2mA	—	—	0.45	V
V _{OH11}	Output High Voltage (Except P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)	I _{OH} = - 1.6mA	2.4	—	—	V
V _{OH12}	Output High Voltage (Except P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)	I _{OH} = - 400μA	V _{CC} - 0.8	—	—	V
V _{OH21}	Output High Voltage (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)	I _{OH} = - 50μA	2.4	—	—	V
V _{OH22}	Output High Voltage (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)	I _{OH} = - 25μA	V _{CC} - 0.8	—	—	V
I _{LI}	Input Leak Current (T ₁ , INT, EA, PS)	V _{SS} ≤ V _{IN} ≤ V _{CC}	—	—	± 10	μA
I _{LI1}	Input Leak Current (SS, RESET)	V _{SS} ≤ V _{IN} ≤ V _{CC}	—	—	- 50	μA
I _{LI2}	Input Leak Current (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)	V _{SS} + 0.45V ≤ V _{IN} ≤ V _{CC}	—	—	- 500	μA
I _{LO}	Output Leak Current (BUS, T ₀) (High impedance condition)	V _{SS} + 0.45V ≤ V _{IN} ≤ V _{CC}	—	—	± 10	μA
ICC1	V _{CC} Supply Current	Normal operation	V _{CC} = 5V, f _{XTAL} = 6MHz	—	10	mA
ICCH1		HALT Mode	V _{IH} = V _{CC} - 0.2V V _{IL} = 0.2V	—	2.5	
ICC2	V _{CC} Supply Current	Normal operation	V _{CC} = 5V, f _{XTAL} = 11MHz	—	15	mA
ICCH2		HALT Mode	V _{IH} = V _{CC} - 0.2V V _{IL} = 0.2V	—	4.0	

4.3 AC Characteristics

TMP80C50AP/C40AP/C50AU

T_{OPR} = -40°C to 85°C, V_{CC} = +5V ± 10%, V_{SS} = 0V, unless otherwise noted.

SYMBOL	PARAMETER	TEST CONDITION	f (t)	11MHz		UNIT
				MIN.	MAX.	
t	Clock Period	Note 2	1/xtal f	90.9	1000	ns
t _{LL}	ALE Pulse Width		3.5t - 170	150	-	ns
t _{AL}	Address Setup Time (ALE)		2t - 110	70	-	ns
t _{LA}	Address Hold Time (ALE)	CL = 20pF	t - 40	50	-	ns
t _{CC1}	Control Pulse Width (RD, WR)		7.5t - 200	480	-	ns
t _{CC2}	Control Pulse Width (PSEN)		6t - 200	350	-	ns
t _{DW}	Data Setup Time (WR)		6.5t - 200	390	-	ns
t _{WD}	Data Hold Time (WR)	CL = 20pF	t - 50	40	-	ns
t _{DR}	Data Hold Time (RD, PSEN)	CL = 20pF	1.5t - 30	0	110	ns
t _{RD1}	Data Input Read Time (RD)		5.5t - 120	-	375	ns
t _{RD2}	Data Input Read Time (PSEN)		4t - 120	-	240	ns
t _{AW}	Address Setup Time (WR)		5t - 150	300	-	ns
t _{AD1}	Address Setup Time (RD)		10t - 170	-	730	ns
t _{AD2}	Address Setup Time (PSEN)		7t - 170	-	460	ns
t _{AFC1}	Address Float Time (RD, WR)	CL = 20pF	2t - 40	140	-	ns
t _{AFC2}	Address Float Time (PSEN)	CL = 20pF	0.5t - 40	10	-	ns
t _{LAFC1}	ALE to Control Time (RD, WR)		3t - 75	200	-	ns
t _{LAFC2}	ALE to Control Time (PSEN)		1.5t - 75	60	-	ns
t _{CA1}	Control to ALE Time (RD, WR, PROG)		t - 65	25	-	ns
t _{CA2}	Control to ALE Time (PSEN)		4t - 70	290	-	ns

AC Characteristics (Continue)

 $T_{OPR} = -40^{\circ}\text{C to } 85^{\circ}\text{C}, V_{CC} = +5\text{V} \pm 10\%, V_{SS} = 0\text{V},$ unless otherwise noted.

SYMBOL	PARAMETER	TEST CONDITION	f (t)	11MHz		UNIT
				MIN.	MAX.	
t_{CP}	Port Control Setup Time (PROG)		$1.5t - 80$	50	—	ns
t_{PC}	Port Control Hold Time (PROG)		$4t - 260$	100	—	ns
t_{PR}	Port 2 Input Data Setup Time (PROG)		$8.5t - 120$	—	650	ns
t_{PF}	Port 2 Input Data Hold Time (PROG)		$1.5t$	0	140	ns
t_{DP}	Port 2 Output Data Setup Time (PROG)		$6t - 290$	250	—	ns
t_{PD}	Port 2 Output Data Hold Time (PROG)		$1.5t - 90$	40	—	ns
t_{PP}	PROG Pulse Width		$10.5t - 250$	700	—	ns
t_{PL}	Port 2 I/O Data Setup Time (ALE)		$4t - 200$	160	—	ns
t_{LP}	Port 2 I/O Data Hold Time (ALE)		$0.5t - 30$	15	—	ns
t_{PV}	Port Output Delay Time (ALE)		$4.5t + 100$	—	510	ns
t_{OPRR}	T_0 Clock Period		$3t$	270	—	ns
t_{CY}	Cycle Time		$15t$	1.36	15.0	ns

Note : 1. Control Output $CL = 80\text{pF}$. BUS Output $CL = 150\text{pF}$.

2. The f (t) assumes 50% duty cycle on $XTAL_1$ and $XTAL_2$.

The Max. Clock frequency is 11MHz. and the Min. Clock frequency is 1MHz.

4.4 Absolute Maximum Ratings

TMP80C50AP-6/TMP80C40AP-6/TMP80C50AU-6

SYMBOL	ITEM	RATING
V _{CC}	V _{CC} Supply Voltage (with respect to GND (V _{SS}))	- 0.5V to + 7V
V _{INA}	Input Voltage (Except EA)	- 0.5V to V _{CC} + 0.5V
V _{INB}	Input Voltage (Only EA)	- 0.5V to 13V
P _D	Power Dissipation (Ta = 85°C)	250mW
T _{SOLDER}	Soldering Temperature (Soldering Timer 10 sec)	260°C
T _{STG}	Storage Temperature	- 65°C to 150°C
T _{OPR}	Operating Temperature	- 40°C to 85°C

4.5 DC Characteristics (I)

TMP80C50AP-6/TMP80C40AP-6/TMP80C50AU-6

T_{OPR} = - 40°C to 85°C, V_{CC} = + 5V ± 10%, V_{SS} = 0V, unless otherwise noted

SYMBOL	PARAMETER		TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{IL}	Input Low Voltage			- 0.5	—	0.8	V
V _{IH}	Input High Voltage (Except XTAL ₁ , XTAL ₂ , RESET, PS)			2.2	—	V _{CC}	V
V _{IH1}	Input High Voltage (XTAL ₁ , XTAL ₂ , RESET, PS)			0.7 x V _{CC}	—	V _{CC}	V
V _{OL}	Output Low Voltage (Except P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		I _{OL} = 1.6mA	—	—	0.45	V
V _{OL1}	Output Low Voltage (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		I _{OL} = 1.2mA	—	—	0.45	V
V _{OH11}	Output High Voltage (Except P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		I _{OH} = - 1.6mA	2.4	—	—	V
V _{OH12}	Output High Voltage (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		I _{OH} = - 400μA	V _{CC} - 0.8	—	—	V
V _{OH21}	Output High Voltage (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		I _{OH} = - 50μA	2.4	—	—	V
V _{OH22}	Output High Voltage (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		I _{OH} = - 25μA	V _{CC} - 0.8	—	—	V
I _{LI}	Input Leak Current (T ₁ , INT, EA, PS)		V _{SS} ≤ V _{IN} ≤ V _{CC}	—	—	± 10	μA
I _{LI1}	Input Leak Current (SS, RESET)		V _{SS} ≤ V _{IN} ≤ V _{CC}	—	—	- 50	μA
I _{LI2}	Input Leak Current (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		V _{SS} + 0.45V ≤ V _{IN} ≤ V _{CC}	—	—	- 500	μA
I _{LO}	Output Leak Current (BUS, T ₀) (High impedance condition)		V _{SS} + 0.45V ≤ V _{IN} ≤ V _{CC}	—	—	± 10	μA
ICC1	V _{CC} Supply Current	Normal operation	V _{CC} = 5V, f _{XTAL} = 6MHz	—	—	10	mA
ICCH1		HALT Mode	V _{IH} = V _{CC} - 0.2V V _{IL} = 0.2V	—	—	2.5	

4.6 DC Characteristics (II)

TMP80C50AP-6/TMP80C40AP-6/TMP80C50AU-6

 $T_{OPR} = -40^{\circ}\text{C}$ to 85°C , $V_{CC} = +5\text{V} \pm 20\%$, $V_{SS} = 0\text{V}$, unless otherwise noted.

SYMBOL	PARAMETER		TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
VIL	Input Low Voltage			-0.5	—	$0.15 \times V_{CC}$	V
VIH	Input High Voltage (Except XTAL ₁ , XTAL ₂ , RESET, PS)			$0.5 \times V_{CC}$	—	V_{CC}	V
VIH1	Input High Voltage (XTAL ₁ , XTAL ₂ , RESET, PS)			$0.7 \times V_{CC}$	—	V_{CC}	V
VOL	Output Low Voltage (Except P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		IOL = 1.6mA	—	—	0.45	V
VOL1	Output Low Voltage (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		IOL = 1.2mA	—	—	0.45	V
VOH12	Output High Voltage (Except P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		IOH = -400μA	$V_{CC} - 0.8$	—	—	V
VOH22	Output High Voltage (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		IOH = -25μA	$V_{CC} - 0.8$	—	—	V
ILI	Input Leak Current (T1, INT, EA, PS)		$V_{SS} \leq V_{IN} \leq V_{CC}$	—	—	± 10	μA
ILI1	Input Leak Current (SS, RESET)		$V_{SS} \leq V_{IN} \leq V_{CC}$	—	—	$\frac{-V_{CC}}{0.1}$	μA
ILI2	Input Leak Current (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		$V_{SS} + 0.45\text{V} \leq V_{IN} \leq V_{CC}$	—	—	$\frac{-V_{CC}}{0.01}$	μA
ILO	Output Leak Current (BUS, T ₀) (High impedance condition)		$V_{SS} + 0.45\text{V} \leq V_{IN} \leq V_{CC}$	—	—	± 10	μA
ICC1	V _{CC} Supply Current	Normal operation	$V_{CC} = 5\text{V}$, $f_{XTAL} = 6\text{MHz}$	—	—	10	mA
ICCH1		HALT Mode	$V_{IH} = V_{CC} - 0.2\text{V}$ $V_{IL} = 0.2\text{V}$	—	—	2.5	

4.7 AC Characteristics

TMP80C50AP-6/TMP80C40AP-6/TMP80C50AU-6

 $T_{OPR} = -40^{\circ}\text{C}$ to 85°C , $V_{CC} = +5\text{V} \pm 20\%$, $V_{SS} = 0\text{V}$, unless otherwise noted.

SYMBOL	PARAMETER	TEST CONDITION	f (t)	6MHz		UNIT
				MIN.	MAX.	
t	Clock Period	Note 2	1/xtal f	166.6	1000	ns
t _{LL}	ALE Pulse Width		3.5t – 170	410	–	ns
t _{AL}	Address Setup Time (ALE)		2t – 110	220	–	ns
t _{LA}	Address Hold Time (ALE)	CL = 20pF	t – 40	120	–	ns
t _{CC1}	Control Pulse Width ($\overline{\text{RD}}$, $\overline{\text{WR}}$)		7.5t – 200	1050	–	ns
t _{CC2}	Control Pulse Width (PSEN)		6t – 200	800	–	ns
t _{DW}	Data Setup Time (WR)		6.5t – 200	880	–	ns
t _{WD}	Data Hold Time (WR)	CL = 20pF	t – 50	120		ns
t _{DR}	Data Hold Time (RD, PSEN)	CL = 20pF	1.5t – 30	0	220	ns
t _{RD1}	Data Input Read Time (RD)		5.5t – 120	–	800	ns
t _{RD2}	Data Input Read Time (PSEN)		4t – 120	–	550	ns
t _{AW}	Address Setup Time (WR)		5t – 150	680	–	ns
t _{AD1}	Address Setup Time (RD)		10t – 170	–	1500	ns
t _{AD2}	Address Setup Time (PSEN)		7t – 170	–	1000	ns
t _{AFC1}	Address Float Time (RD, WR)	CL = 20pF	2t – 40	290	–	ns
t _{AFC2}	Address Float Time (PSEN)	CL = 20pF	0.5t – 40	40	–	ns
t _{LAFC1}	ALE to Control Time (RD, WR)		3t – 75	420	–	ns
t _{LAFC2}	ALE to Control Time (PSEN)		1.5t – 75	175	–	ns
t _{CA1}	Control to ALE Time (RD, WR PROG)		t – 65	100	–	ns
t _{CA2}	Control to ALE Time (PSEN)		4t – 70	590	–	ns

AC Characteristics (Continue)

$T_{OPR} = -40^{\circ}\text{C}$ to 85°C , $V_{CC} = +5\text{V} \pm 20\%$, $V_{SS} = 0\text{V}$, unless otherwise noted.

SYMBOL	PARAMETER	TEST CONDITION	f (t)	6MHz		UNIT
				MIN.	MAX.	
t_{CP}	Port Control Setup Time (PROG)		$1.5t - 80$	170	—	ns
t_{PC}	Port Control Hold Time (PROG)		$4t - 260$	400	—	ns
t_{PR}	Port 2 Input Data Setup Time (PROG)		$8.5t - 120$	—	1290	ns
t_{PF}	Port 2 Input Data Hold Time (PROG)		$1.5t$	0	250	ns
t_{DP}	Port 2 Output Data Setup Time (PROG)		$6t - 290$	710	—	ns
t_{PD}	Port 2 Output Data Hold Time (PROG)		$1.5t - 90$	160	—	ns
t_{PP}	PROG Pulse Width		$10.5t - 250$	1500	—	ns
t_{PL}	Port 2 I/O Data Setup Time (ALE)		$4t - 200$	460	—	ns
t_{LP}	Port 2 I/O Data Hold Time (ALE)		$0.5t - 30$	130	—	ns
t_{PV}	Port Output Delay Time (ALE)		$4.5t + 100$	—	850	ns
t_{OPRR}	T_0 Clock Period		$3t$	500	—	ns
t_{CY}	Cycle Time		$15t$	2.5	15.0	ns

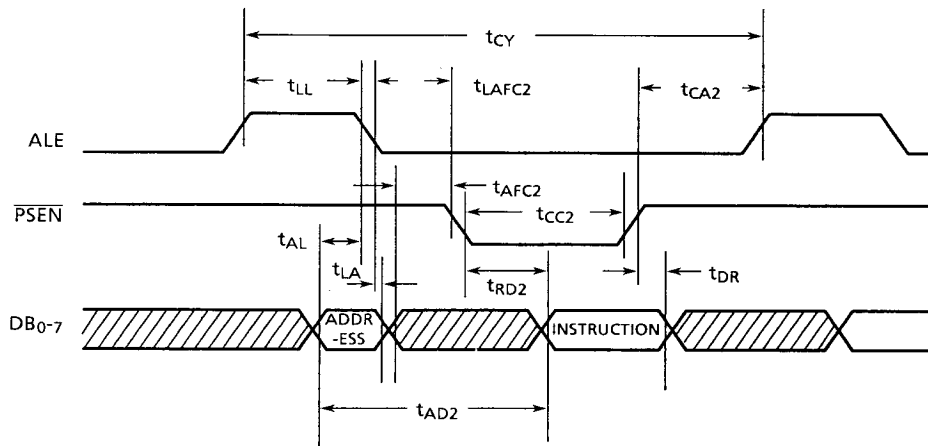
Note : 1. Control Output $CL = 80\text{pF}$. BUS Output $CL = 150\text{pF}$.

2. The f (t) assumes 50% duty cycle on $XTAL_1$ and $XTAL_2$.

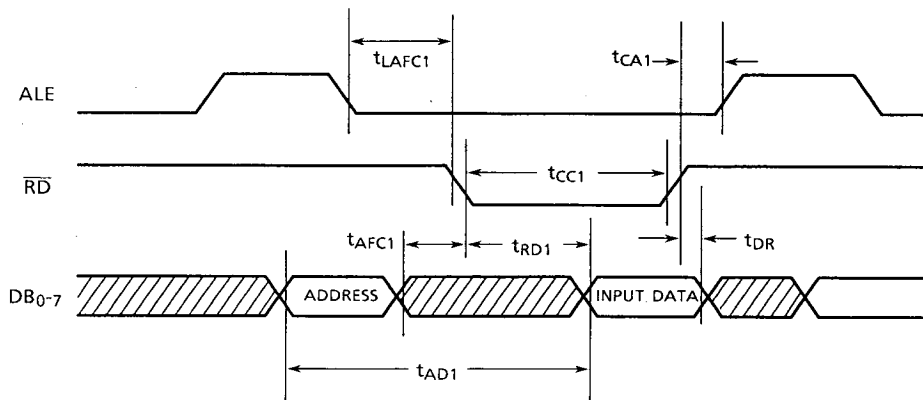
The Max. Clock frequency is 11MHz. and the Min. Clock frequency is 1MHz.

4.8 Timing Waveform

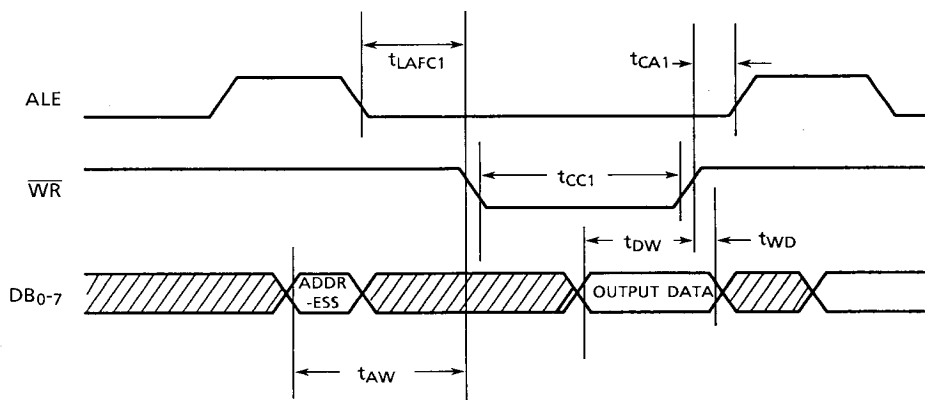
A. Instruction Fetch from External Program Memory



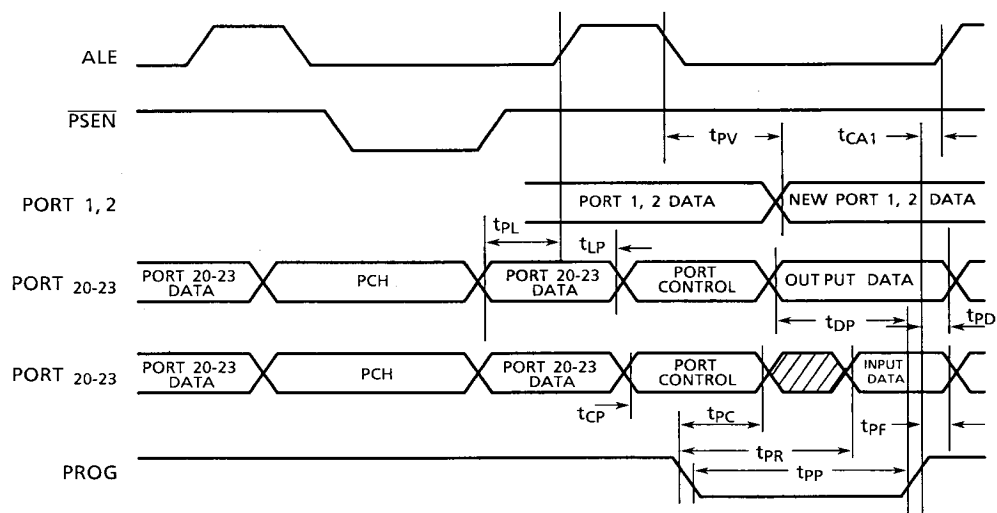
B. Read from External Data Memory



C. Write into External Data Memory



D. Timing of Port 2 during Expander Instruction Execution



4.9 Stand-By Function

4.9.1 Power Down Mode (I) Data Hold Mode in RAM

The operation of oscillation circuit is suspended by setting $\overline{PS}$ terminal to low level after $\overline{RESET}$ terminal has been set to low level. Consequently, all the data in RAM area can be held in low power consumption.

The minimum hold voltage of V_{CC} in this mode is 2V.

$\overline{PS}$ terminal is set to high level to resume oscillation after V_{CC} has been reset to 5V, and then $\overline{RESET}$ terminal is set to high level, thus, the normal mode is restarted from the initialize operation (address 0).

(1) DC Characteristics

TMP80C50AP/C40AP/C50AU

TMP80C50AP-6/C40AP-6/C50AU-6

: $T_{OPR} = -40^{\circ}\text{C}$ to 85°C , $V_{SS} = 0\text{V}$

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VSB1	Standby Voltage (1)		2.0	—	6.0	V
ISB1	Standby Current (1)	$V_{CC} = 5\text{V}$, $V_{IH} = V_{CC}$ -0.2V , $V_{IL} = 0.2\text{V}$	—	0.5	10	μA

(2) AC Characteristics

TMP80C50AP/C40AP/C50AU

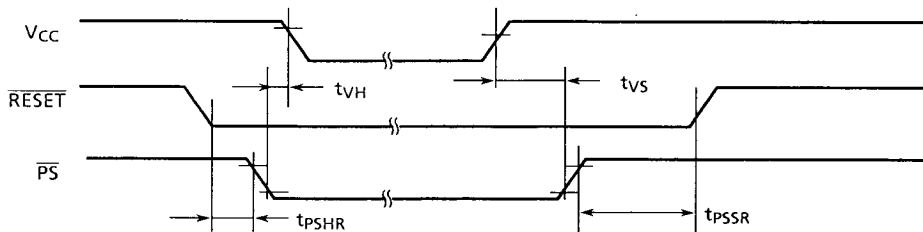
TMP80C50AP-6/C40AP-6/C50AU-6

: $V_{CC} = 5\text{V} \pm 10\%$, $V_{SS} = 0\text{V}$: $V_{CC} = 5\text{V} \pm 20\%$, $V_{SS} = 0\text{V}$

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
tpSHR	Power Save Hold Time ($\overline{RESET}$)		10	—	—	μs
tpSSR	Power Save Setup Time ($\overline{RESET}$)		10	—	—	ms
tvH	V_{CC} Hold Time ($\overline{PS}$)		5	—	—	μs
tvS	V_{CC} Setup Time ($\overline{PS}$)		5	—	—	μs

Note : $t_{CY} = 2.5\mu\text{s}$ ($f_{XTAL} = 6\text{MHz}$)

(3) Timing Waveform



4.9.2 Power Down Mode (II) ALL Data Hold Mode

The operation of oscillation circuit is suspended by setting $\overline{PS}$ terminal to low level after $\overline{SS}$ terminal has been set to low level. Consequently, all data can be held in low power consumption.

The minimum hold voltage of V_{CC} in this mode is 3V.

$\overline{PS}$ terminal is set to high level to resume oscillation after V_{CC} has been reset to 5V, and then $\overline{SS}$ terminal is set to high level, thus, the normal mode is restarted continuously from the state just before the power down mode (II).

(1) DC Characteristics

TMP80C50AP/C40AP/C50AU : $TOPR = -40^{\circ}C$ to $85^{\circ}C$, $V_{SS} = 0V$
TMP80C50AP-6/C40AP-6/C50AU-6

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VSB2	Standby Voltage (2)		3.0	—	6.0	V
ISB2	Standby Current (2)	$V_{CC} = 5V$, $V_{IH} = V_{CC} - 0.2V$, $V_{IL} = 0.2V$	—	0.5	10	μA

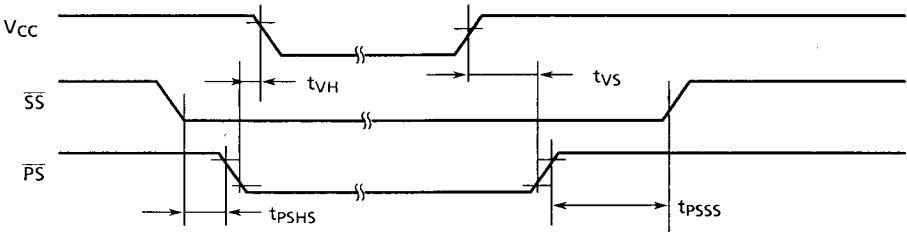
(2) AC Characteristics

TMP80C50AP/C40AP/C50AU : $V_{CC} = 5V \pm 10\%$, $V_{SS} = 0V$
TMP80C50AP-6/C40AP-6/C50AU-6 : $V_{CC} = 5V \pm 20\%$, $V_{SS} = 0V$

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
tpSHS	Power Save Hold Time ($\overline{SS}$)		10	—	—	μs
tpSSS	Power Save Setup Time ($\overline{SS}$)		10	—	—	ms
tvH	V_{CC} Hold Time ($\overline{PS}$)		5	—	—	μs
tvS	V_{CC} Setup Time ($\overline{PS}$)		5	—	—	μs

Note : $t_{CY} = 2.5\mu s$ ($f_{XTAL} = 6MHz$)

(3) Timing Waveform



4.9.3 HALT MODE

(1) HALT INSTRUCTION

OP code is "01H". HALT INSTRUCTION is an additional instruction to the standard 8048/8049 instruction set.

(2) Entry to HALT MODE

On the execution of HALT INSTRUCTION, TMP80C50A/TMP80C40A enter HALT MODE.

(3) Status in HALT MODE

The oscillator continues its operation, however, the internal clocks and internal logic values just prior to the execution of HALT INSTRUCTION are maintained. Power consumption in HALT MODE is less than 50% of normal operation. The status of each pins are described in the following table.

(4) Release from HALT MODE

HALT MODE is released by either of two signals ($\overline{\text{RESET}}$, $\overline{\text{INT}}$).

(4.1) $\overline{\text{RESET}}$ Release Mode : An active $\overline{\text{RESET}}$ input signal causes the normal reset function. TMP80C50A/TMP80C40A start the program at address "000 H".

(4.2) $\overline{\text{INT}}$ Release Mode : An active $\overline{\text{INT}}$ input signal causes the normal operation.

- In case of interrupt enable mode (EI MODE), TMP80C50A/TMP80C40A execute the interrupt service routine, after the execution of one instruction which is located at the next address after HALT INSTRUCTION.

- In case of interrupt disable mode (DI MODE), TMP80C50A/TMP80C40A execute normal operation from the next address after HALT INSTRUCTION.

(5) Supply Voltage Range in HALT MODE

The operating supply voltage range and the operating temperature range are same as in normal operation.

TMP80C50AP/C40AP/C50AU : $V_{CC}=5V \pm 10\%$

TMP80C50AP-6/C40AP-6/C50AU-6 : $V_{CC}=5V \pm 20\%$

4.9.4 Pin Status In Power Down Mode (I) (II)

PIN NAME	STATUS
DB ₀ ~DB ₇	High impedance Input disabled
P ₁₀ ~P ₁₇	
P ₂₀ ~P ₂₇	
T ₀	High Impedance, input disabled
T ₁	Input disabled
XTAL ₁	High impedance
XTAL ₂	Output "High" level
RESET, SS	Input disabled when oscillator is stopped. Pull-up transistors turn off.
INT, EA	Input disabled when oscillator is stopped.
RD, WR, ALE PROG, PSEN	High impedance

4.9.5 Pin Status In HALT MODE

PIN NAME	STATUS
DB ₀ ~DB ₇	Values prior to the execution of HALT INSTRUCTION are maintained.
P ₁₀ ~P ₁₇	
P ₂₀ ~P ₂₇	
T ₀	Status prior to the execution of HALT INSTRUCTION is maintained.
T ₁	Input disabled
XTAL ₁ , XTAL ₂	Continue oscillation
RESET, INT	Input enabled
SS, EA	Input disabled
RD, WR, PROG, PSEN	Output "High" level
ALE	Output "Low" level

5. OSCILLATOR

QUARTZ CRYSTAL

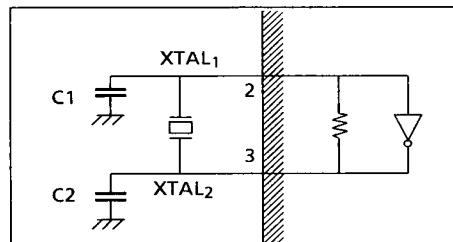
$f = 1\text{MHz to } 4\text{MHz} : C1 = C2 = 30\text{pF}$

$f = 4\text{MHz to } 11\text{MHz} : C1 = C2 = 20\text{pF}$

CERAMIC RESONATOR

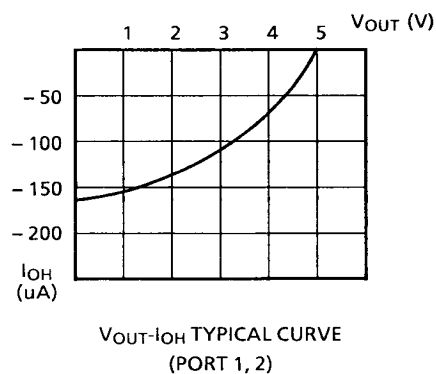
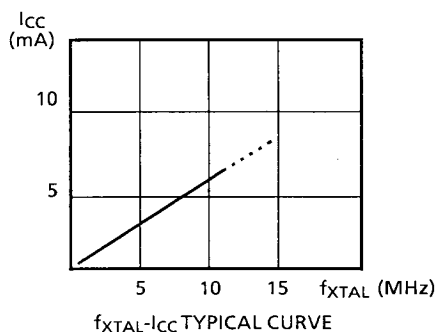
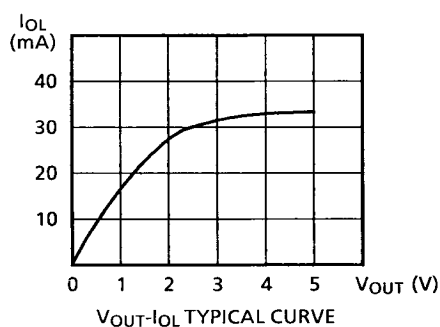
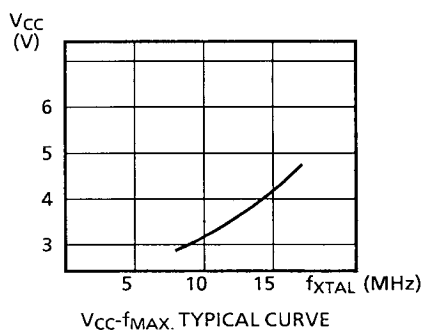
$f = 1\text{MHz to } 3\text{MHz} : C1 = C2 = 100\text{pF}$

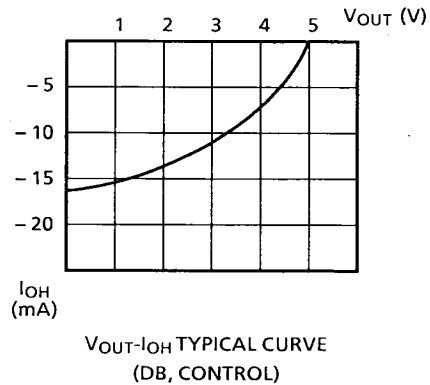
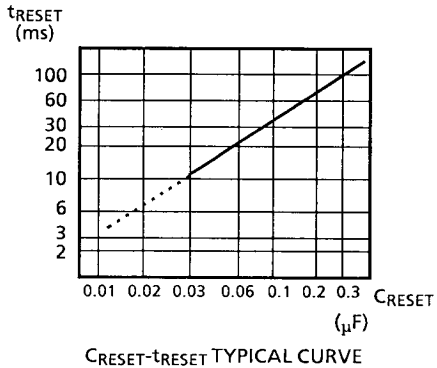
$f = 3\text{MHz to } 11\text{MHz} : C1 = C2 = 30\text{pF}$



6. TYPICAL CHARACTERISTICS

$V_{CC} = 5\text{V}$, $T_a = 25^\circ\text{C}$, unless otherwise noted.



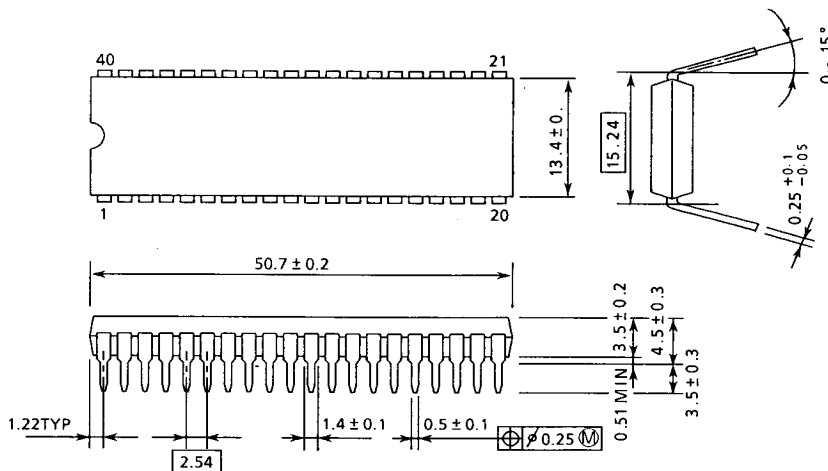


7. OUTLINE DRAWING

7.1 Outline Drawing For TMP80C50AP/-6, TMP80C40AP/-6 (DIP : Dual Inline Package)

DIP40-P-600

Unit : mm

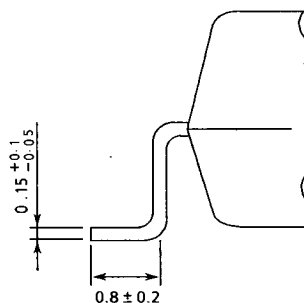
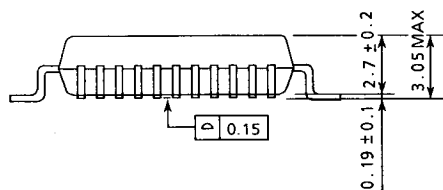
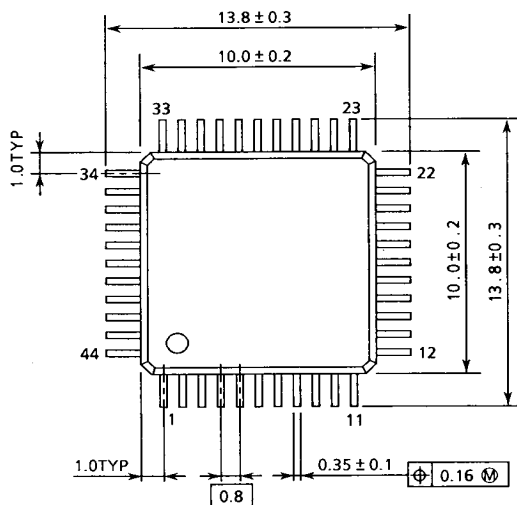


- Note:
1. This dimension is measured at the center of bending point of leads.
 2. Each lead pitch is 2.54mm, and all the leads are located within ± 0.25 mm from their theoretical positions with respect to No.1 and No.40 leads.

7.2 Outline Drawing For TMP80C50AU/-6 (Micro Flat Package)

QFP44-P-1010A

Unit : mm



Note:

1. The above dimensions don't include the burr of package and the residue of tie-bar cut. The burr of package and the residue of tie-bar cut should be 0.15 mm (Max.).
2. Applied to the lead flat portion.